

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Applicants: Michael S. Leung et al. Confirmation No. 8955  
Serial No. 10/666,399 Examiner: Le, Thao X.  
Filed: September 18, 2003 Art Unit: 2814  
Docket No. P0298US-7

Title: MOLDED CHIP FABRICATION METHOD AND APPARATUS

MAIL STOP AMENDMENT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

AMENDMENT AND RESPONSE

Sir:

In response to the Office Action mailed on September 30, 2005, please amend the above-identified application as follows:

**AMENDMENTS TO THE CLAIMS** are reflected in A Listing of the Claims shown beginning on page 2 of this paper.

**REMARKS AND ARGUMENTS** begin on page 9 of this paper.